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Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









HMC627LP5 / 627LP5E





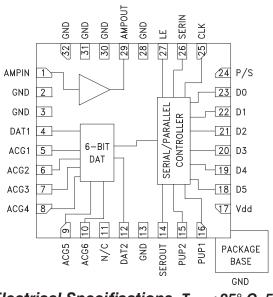
0.5 dB LSB GaAs MMIC 6-BIT DIGITAL VARIABLE GAIN AMPLIFIER, 50 MHz - 1 GHz

Typical Applications

The HMC627LP5(E) is ideal for:

- Cellular/3G Infrastructure
- WiBro / WiMAX / 4G
- Microwave Radio & VSAT
- Test Equipment and Sensors
- IF & RF Applications

Functional Diagram



Features

-11.5 to 20 dB Gain Control in 0.5 dB Steps

Power-up State Selection

High Output IP3: +36 dBm

TTL/CMOS Compatible

Serial, Parallel, or latched Parallel Control

±0.25 dB Typical Gain Step Error

Single +5V Supply

32 Lead 5x5mm SMT Package: 25mm²

General Description

The HMC627LP5(E) is a digitally controlled variable gain amplifier which operates from 50 MHz to 1 GHz, and can be programmed to provide anywhere from 11.5 dB attenuation, to 20 dB of gain, in 0.5 dB steps. The HMC627LP5(E) delivers noise figure of 4.3 dB in its maximum gain state, with output IP3 of up to +36 dBm in any state. The dual mode gain control interface accepts either three wire serial input or 6 bit parallel word. The HMC627LP5(E) also features a user selectable power up state and a serial output for cascading other Hittite serially controlled components. The HMC627LP5(E) is housed in a RoHS compliant 5x5 mm QFN leadless package, and requires no external matching components.

Electrical Specifications, $T_A = +25^{\circ}$ C, 50 Ohm System Vdd = +5V, Vs= +5V

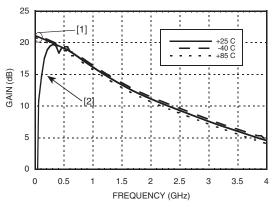
| Dovometer | Min. | Тур. | Max. | Min. | Тур. | Max. | Units |
|--|----------|--|-------|----------------------------------|-----------|------|-------|
| Parameter | 50 - 350 | | | 350 - 1000 | | | MHz |
| Gain (Maximum Gain State) | 18 | 20 | | 15 | 17.5 | | dB |
| Gain Control Range | | 31.5 | | | 31.5 | | dB |
| Input Return Loss | | 18 | | | 17 | | |
| Output Return Loss | 20 | 12 | | | 12 | | dB |
| Gain Accuracy: (Referenced to Maximum Gain State) All Gain States | ± (0.2 + | 00MHz, 250 M 3% of Gain S 00 MHZ - 250 2% of Gain S |) MHz | ± (0.3 + 3% of Gain Setting) Max | | dB | |
| Output Power for 1 dB Compression | 18 | 20 | | 16 | 20 | | dBm |
| Output Third Order Intercept Point (Two-Tone Input Power= 0 dBm Each Tone) | 33 | 36 | | 33 | 36 | | dBm |
| Noise Figure | | 4.3 | | | 4.3 | | dB |
| Switching Characteristics tRISE, tFall (10 / 90% RF) tON, tOFF (Latch Enable to 10 / 90% RF) | | 170 70 | | | 170 70 | | ns |
| Supply Current (Idd) | | 90 | 110 | | 90 | 110 | mA |

For price, delivery and to place orders: Hittite Microwave Corporation, 20 Alpha Road, Chelmsford, MA 01824
Phone: 978-250-3343 Fax: 978-250-3373 Order On-line at www.hittite.com
Application Support: Phone: 978-250-3343 or apps@hittite.com

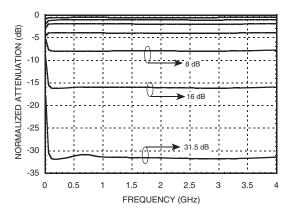




Maximum Gain vs. Frequency [1]

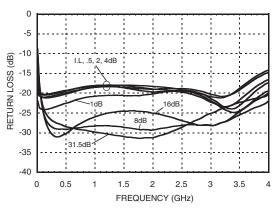


Normalized Attenuation vs. Frequency (Only Major States are Shown)



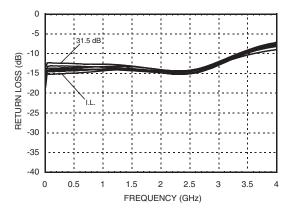
Input Return Loss [1]

(Only Major States are Shown)



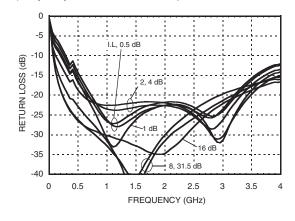
Output Return Loss [1]

(Only Major States are Shown)



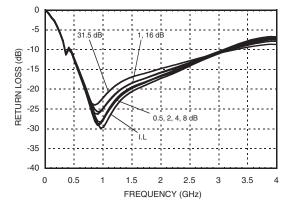
Input Return Loss [2]

(Only Major States are Shown)



Output Return Loss [2]

(Only Major States are Shown)



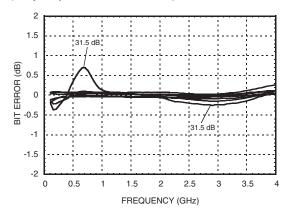
- [1] Tested with broadband bias tee on RF ports and C1 = 10,000pF
- [2] C1, C6 and C8 = 100pF, L1 = 270nF



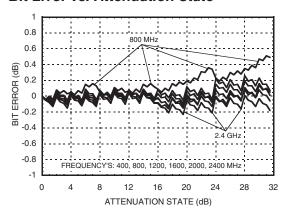


Bit Error vs. Frequency [2]

(Only Major States are Shown)

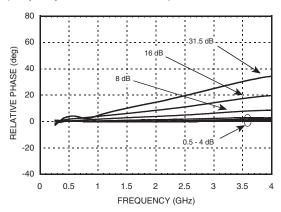


Bit Error vs. Attenuation State [2]



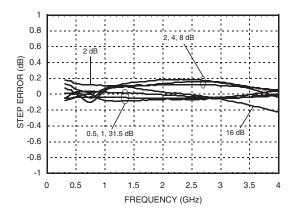
Normal Relative Phase vs. Frequency [2]

(Only Major States are Shown)



Step Error vs. Frequency [2]

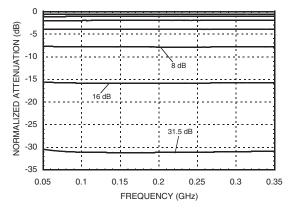
(Only Major States are Shown)



Maximum Gain vs. Frequency[3]

25 20 20 15 10 5 0 0.05 0.1 0.15 0.2 0.25 0.3 0.35 FREQUENCY (GHz)

Normalized Attenuation vs. Frequency [3]

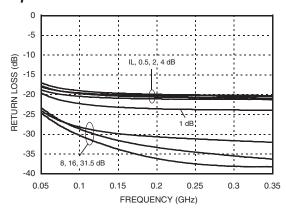


- [1] Tested with broadband bias tee on RF ports and C1 = 10,000pF
- [2] C1, C6 and C8 = 100pF, L1 = 270nF
- [3] C1, C6, C8 = 3300pF; C3, C4 & C5 = 330pF; L1 = 560nH

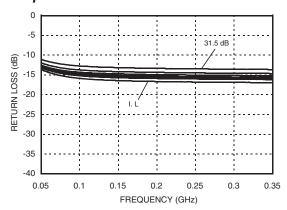




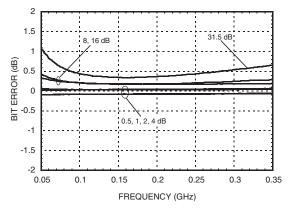
Input Return Loss [3]



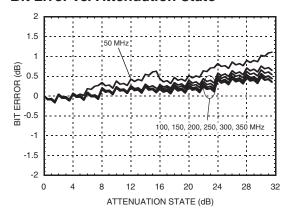
Output Return Loss [3]



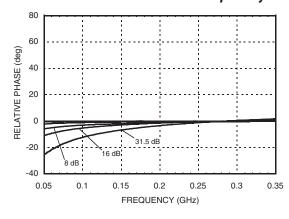
Bit Error vs. Frequency [3]



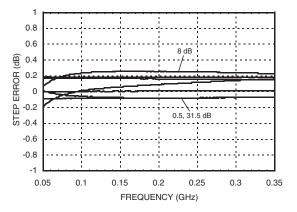
Bit Error vs. Attenuation State [3]



Normal Relative Phase vs. Frequency [3]



Step Error vs. Frequency [3]



[3] C1, C6, C8 = 3300pF; C3, C4 & C5 = 330pF; L1 = 560nH



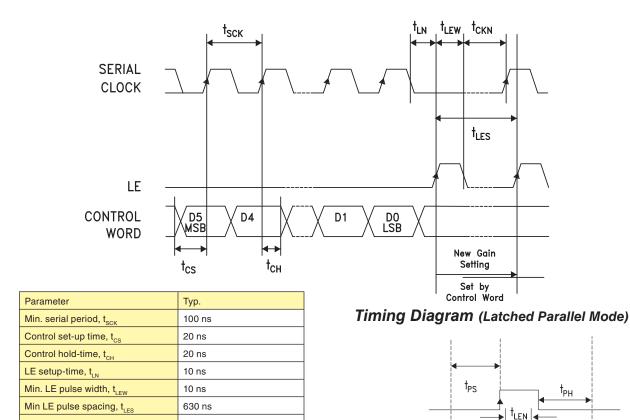


Serial Control Interface

The HMC627LP5(E) contains a 3-wire SPI compatible digital interface (SERIN, CLK, LE). It is activated when P/S is kept high. The 6-bit serial word must be loaded MSB first. The positive-edge sensitive CLK and LE requires clean transitions. If mechanical switches were used, sufficient debouncing should be provided. When LE is high, 6-bit data in the serial input register is transferred to the attenuator. When LE is high CLK is masked to prevent data transition during output loading.

When P/S is low, 3-wire SPI interface inputs (SERIN, CLK, LE) are disabled and serial input register is loaded asynchronously with parallel digital inputs (D0-D5). When Le is high, 6-bit parallel data is transferred to the attenuator.

For all modes of operations, the DVGA state will stay constant while LE is kept low.



Parallel Mode (Direct Parallel Mode & Latched Parallel Mode)

Note: The parallel mode is enabled when P/S is set to low.

10 ns

0 ns

10 ns 2 ns

Serial clock hold-time from LE, t

Latch Enable Minimum Width, t,

Hold Time, tp.

Setup Time, tps

Direct Parallel Mode - The attenuation state is changed by the Control Voltage Inputs directly. The LE (Latch Enable) must be at a logic high to control the attenuator in this manner.

PARALLEL CONTROL

D0-D5

Latched Parallel Mode - The attenuation state is selected using the Control Voltage Inputs and set while the LE is in the Low state. The attenuator will not change state while LE is Low. Once all Control Voltage Inputs are at the desired states the LE is pulsed. See timing diagram above for reference.





Power-Up States

If LE is set to logic LOW at power-up, the logic state of PUP1 and PUP2 determines the power-up state of the part per PUP truth table. If the LE is set to logic HIGH at power-up, the logic state of D0-D5 determines the power-up state of the part per truth table. The DVGA latches in the desired power-up state approximately 200 ms after power-up.

Power-On Sequence

The ideal power-up sequence is: GND, Vdd, digital inputs, RF inputs. The relative order of the digital inputs are not important as long as they are powered after Vdd / GND

Absolute Maximum Ratings

| RF Input Power [1] | 11.5 dBm (T = +85 °C) |
|--|-----------------------|
| Digital Inputs (Reset, Shift Clock, Latch Enable & Serial Input) | -0.5V to Vdd +0.5V |
| Bias Voltage (Vdd) | 5.6V |
| Collector Bias Voltage (Vcc) | 5.5V |
| Channel Temperature | 150 °C |
| Continuous Pdiss (T = 85 °C) (derate 9 mW/°C above 85 °C) [1] | 0.593 W |
| Thermal Resistance | 110 °C/W |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -40 to +85 °C |

^[1] At max gain settling

Bias Voltage

| Vdd (V) | Idd (Typ.) (mA) |
|---------|-----------------|
| +5 | 2 |
| Vs (V) | Is (mA) |
| +5 | 88 |



PUP Truth Table

| LE | PUP1 | PUP2 | Gain Relative to Maximum Gain |
|----|------|------|----------------------------------|
| 0 | 0 | 0 | -31.5 |
| 0 | 1 | 0 | -24 |
| 0 | 0 | 1 | -16 |
| 0 | 1 | 1 | Insertion Loss |
| 1 | Х | Х | 0 to -31.5 dB |

Note: The logic state of D0 - D5 determines the power-up state per truth table shown below when LE is high at power-up.

Truth Table

| | Control Voltage Input | | | | | |
|------|-----------------------|------|------|------|------|--------------------------------|
| D5 | D4 | D3 | D2 | D1 | D0 | Relative to Maximum Gain |
| High | High | High | High | High | High | 0 dB |
| High | High | High | High | High | Low | -0.5 dB |
| High | High | High | High | Low | High | -1 dB |
| High | High | High | Low | High | High | -2 dB |
| High | High | Low | High | High | High | -4 dB |
| High | Low | High | High | High | High | -8 dB |
| Low | High | High | High | High | High | -16 dB |
| Low | Low | Low | Low | Low | Low | -31.5 dB |

Any combination of the above states will provide a reduction in gain approximately equal to the sum of the bits selected.

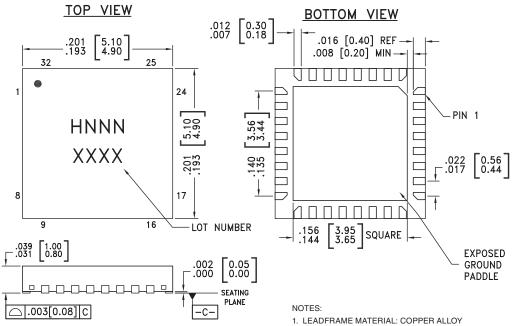
Control Voltage Table

| State | Vdd = +3V | Vdd = +5V |
|-------|-------------------|-------------------|
| Low | 0 to 0.5V @ <1 μA | 0 to 0.8V @ <1 μA |
| High | 2 to 3V @ <1 μA | 2 to 5V @ <1 μA |





Outline Drawing



- 2. DIMENSIONS ARE IN INCHES [MILLIMETERS]
- 3. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
 PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm.
- ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [3] |
|-------------|--|---------------|------------|---------------------|
| HMC627LP5 | Low Stress Injection Molded Plastic | Sn/Pb Solder | MSL1 [1] | H627 XXXX |
| HMC627LP5E | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [2] | H627 XXXX |

- [1] Max peak reflow temperature of 235 $^{\circ}\text{C}$
- [2] Max peak reflow temperature of 260 $^{\circ}\text{C}$
- [3] 4-Digit lot number XXXX





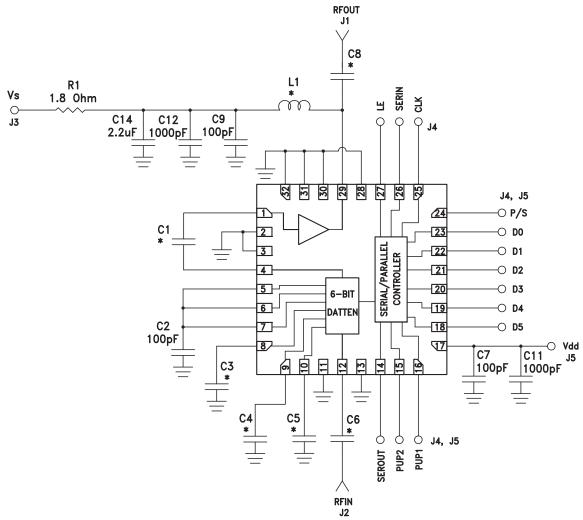
Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|--------------------------|---------------------------|--|--------------------------|
| 1 | AMPIN | This pin is DC coupled. An off chip DC blocking capacitor is required. | AMPIN |
| 29 | AMPOUT | RF output and DC bias (Vcc) for the output stage of the amplifier. | |
| 2, 3, 13, 28, 30 - 32 | GND | These pins and package bottom must be connected to RF/DC ground. | GND = |
| 4, 12 | ATTIN, ATTOUT | These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required. Select value based on lowest frequency of operation. | ATTIN, O ATTOUT |
| 5 - 10 | ACG1 - ACG6 | External capacitors to ground is required. Select value for lowest frequency of operation. Place capacitor as close to pins as possible. | |
| 11 | N/C | No Connection | |
| 14 | SEROUT | Serial input data delayed by 6 clock cycles. | Vdd O SEROUT |
| 15, 16 | PUP2, PUP1 | | Vdd O |
| 18 - 23 | D5, D4, D3, D2, D1, D0 | | SERIN - |
| 24 | P/S | | PUP2, PUP1 D0-D5 0 |
| 25 | CLK | | P/S CLK |
| 26 | SERIN | | LE H |
| 27 | LE | | _ |
| 17 | Vdd | Supply Voltage | |





Application Circuit



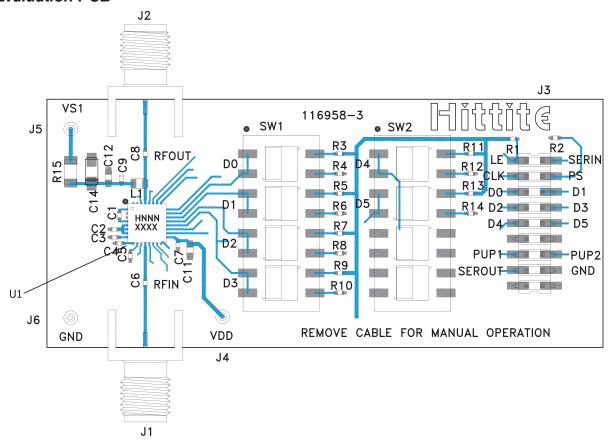
Components for Selected Frequencies

| Tuned Frequency | 50 -350 MHz | 350 - 1000 MHz |
|-----------------|-------------|----------------|
| Evaluation PCB | 121394 | 118329 |
| C1, C6, C8 | 3300pF | 100pF |
| C3, C4, C5 | 330pF | 100pF |
| L1 | 560nH | 270nH |





Evaluation PCB



List of Materials for Evaluation [3]

| Item | Description |
|-----------------|--------------------------------------|
| J1 - J2 | PCB Mount SMA Connectors |
| J3 | 18 Pin DC Connector |
| J4 - J6 | DC Pin |
| C1, C3 - C6, C8 | Capacitor, 0402 Pkg.[3] |
| C2, C7. C9 | 100pF Capacitor. 0402 Pkg. |
| C11 - C12 | 1000 pF Capacitor, 0402 Pkg. |
| C14 | 2.2 μF Capacitor, CASE A Pkg. |
| R1 - R14 | 100 kOhm Resistor, 0402 Pkg. |
| R15 | 1.8 Ohm Resistor, 1206 Pkg. |
| L1 | Inductor, 0603 Pkg. [3] |
| SW1, SW2 | SPDT 4 Position DIP Switch |
| U1 | HMC627LP5(E) Variable Gain Amplifier |
| PCB [2] | 116958 Evaluation PCB |

[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Arlon 25FR, FR4

[3] Please reference Components for Selected Frequencies Table

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.